

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10597919
<b>Filing Date:</b>	11-Aug-2006
<b>Title of Invention:</b>	MULTILAYER SUBSTRATE WITH BUILT-IN-CHIP-TYPE ELECTRONIC COMPONENT AND METHOD FOR MANUFACTURING THE SAME
<b>First Named Inventor/Applicant Name:</b>	Osamu Chikagawa
<b>Filer:</b>	Christopher Andrew Bennett/Satoko Sakiyama
<b>Attorney Docket Number:</b>	36856.1458

Filed as Large Entity

### **U.S. National Stage under 35 USC 371 Filing Fees**

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				
Utility Appl issue fee	1501	1	1510	1510
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Extension-of-Time:</b>				
<b>Miscellaneous:</b>				
<b>Total in USD (\$)</b>				<b>1810</b>